

7.0V to 9.5V

15mA(Typ)

0.005%(Typ)

2.3Vrms(Typ)

-100dB(Typ)

6µVrms(Typ)

2µVrms(Typ)

-40°C to +85°C

+0dB to -40dB

## Sound Processor with Built-in 2-band Equalizer BD37512FS

#### **General Description**

BD37512FS is a sound processor with built-in 2-band equalizer for car audio. The functions are 4ch stereo input selector, input-gain control, main volume and 4ch fader volume. Moreover, its "Advanced switch circuit", which is an original ROHM technology, can reduce various switching noise (ex. No-signal, low frequency like 20Hz & large signal inputs). "Advanced switch" makes control of microcomputer easier, supporting the construction of a high quality car audio system.

#### Features

- Reduce switching noise of mute, main volume, fader volume, bass, trebles by using advanced switch circuit
- Built-in 1 differential input selector and 3 single-ended input selectors.
- Built-in ground isolation amplifier inputs, ideal for external stereo input.
- Decrease the number of external components due to built-in 2-band equalizer filter.
- It is possible to adjust the gain of the bass and treble up to ±20dB with 1 dB step gain adjustment.
- Energy-saving design resulting in low current consumption, by utilizing the Bi-CMOS process. It has the advantage in quality over scaling down the power heat control of the internal regulators.
- Input terminals and output terminals are organized and separately laid out to keep the signal flow in one direction which results in simpler and smaller PCB layout.
- It is possible to control the I<sup>2</sup>C BUS by 3.3V / 5V.

## Applications

It is optimal for use in car audio systems. It can also be used for audio equipment of mini Compo, micro Compo, TV, etc.

## Key Specifications

- Power Supply Voltage Range:
- Circuit Current (No Signal):
- Total Harmonic Distortion:
- Maximum Input Voltage:
- Cross-talk Between Selectors:
- Volume Control Range:
- Output Noise Voltage:
- Residual Output Noise Voltage:
- Operating Temperature Range:

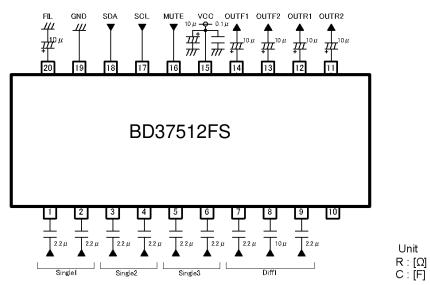
## Package

## W(Typ) x D(Typ) x H(Max)

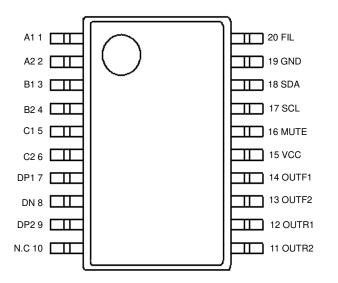


OProduct structure : Silicon monolithic integrated circuit OThis product has no designed protection against radioactive rays

## **Typical Application Circuit**

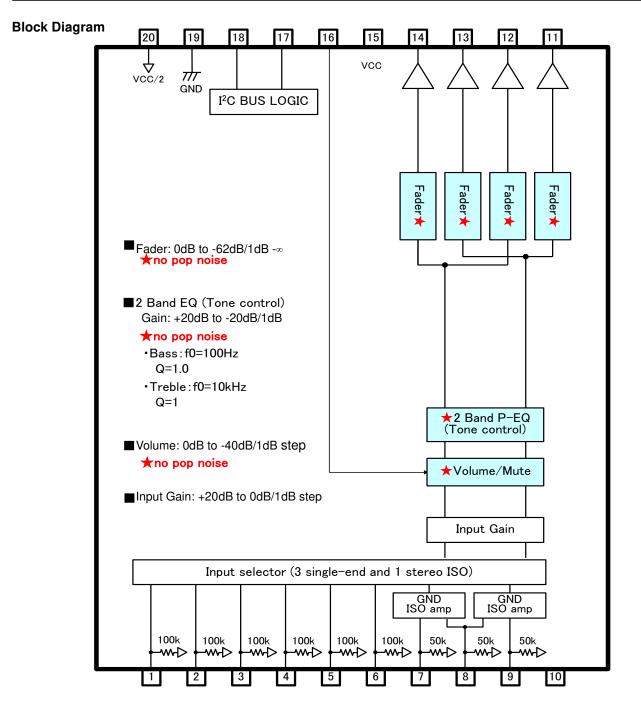


## **Pin Configuration**



## **Pin Descriptions**

Pin No.	Pin Name	Description	Pin No.	Pin Name	Description
1	A1	A input terminal of 1ch	11	OUTR2	Rear output terminal of 2ch
2	A2	A input terminal of 2ch	12	OUTR1	Rear output terminal of 1ch
3	B1	B input terminal of 1ch	13	OUTF2	Front output terminal of 2ch
4	B2	B input terminal of 2ch	14	OUTF1	Front output terminal of 1ch
5	C1	C input terminal of 1ch	15	VCC	Power supply terminal
6	C2	C input terminal of 2ch	16	MUTE	External compulsory mute terminal
7	DP1	D positive input terminal of 1ch	17	SCL	I <sup>2</sup> C Communication clock terminal
8	DN	D negative input terminal	18	SDA	I <sup>2</sup> C Communication data terminal
9	DP2	D positive input terminal of 2ch	19	GND	GND terminal
10	N.C.	No Connection	20	FIL	VCC/2 terminal



## Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Power Supply Voltage	V <sub>CC</sub>	10.0	V
Input Voltage	VIN	V <sub>CC</sub> +0.3 to GND-0.3	V
Power Dissipation	Pd	0.94 <sup>(Note)</sup>	W
Storage Temperature	Tstg	-55 to +150	°C

(Note) This value derates by 7.5mW/°C for Ta=25°C or more when ROHM standard board is used.

Thermal resistance  $\theta_{ja} = 133.3(^{\circ}C/W)$ ROHM Standard board

Size : 70 x 70 x 1.6(mm<sup>3</sup>) Material : A FR4 grass epoxy board(3% or less of copper foil area)

Caution: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

## **Recommended Operating Conditions**

Parameter	Symbol	Min	Тур	Max	Unit
Power Supply Voltage	V <sub>CC</sub>	7.0	-	9.5	V
Temperature	Topr	-40	-	+85	°C

## **Electrical Characteristics**

(Unless specified otherwise, Ta=25°C, V<sub>CC</sub>=8.5V, f=1kHz, V<sub>IN</sub> =1Vrms, Rg=600Ω, R<sub>L</sub>=10kΩ, A input, Input gain 0dB, Mute OFF, Volume 0dB, Tone control 0dB, Loudness 0dB, Fader 0dB)

				Limit				
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
	Circuit Current	la	-	15	30	mA	No signal	
	Voltage Gain	Gv	-1.5	0	1.5	dB	Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> )	
	Channel Balance	CB	-1.5	0	1.5	dB	$CB = Gv_1 - Gv_2$	
	Total Harmonic Distortion	THD+N1	-	0.005	0.05	%	V <sub>OUT</sub> =1VRMS BW=400Hz-30KHz	
RAL	Output Noise Voltage *	V <sub>NO1</sub>	-	6	25	µVrms	Rg = 0Ω BW = IHF-A	
GENERAL	Residual Output Noise Voltage *	VNOR	-	2	10	μVrms	Fader = -∞dB Rg = 0Ω BW = IHF-A	
	Cross-talk Between Channels *	СТС	-	-100	-90	dB	$ \begin{array}{l} Rg = 0\Omega \\ CTC = 20 log(V_{OUT}/V_{IN}) \\ BW = IHF-A \end{array} $	
	Ripple Rejection	RR	-	-70	-40	dB	f=1kHz V <sub>RR</sub> =100mVrms RR=20log(V <sub>CC</sub> IN/V <sub>OUT</sub> )	
	Input Impedance(A, B, C)	RIN_S	70	100	130	kΩ		
	Input Impedance (D)	R <sub>IN_D</sub>	35	50	65	kΩ		
SELECTOR	Maximum Input Voltage	VIM	2.1	2.3	-	Vrms	V <sub>IM</sub> at THD+N(V <sub>OUT</sub> )=1% BW=400Hz-30KHz	
JT SELE	Cross-talk Between Selectors *	CTS	-	-100	-90	dB	$ \begin{array}{l} Rg = 0\Omega \\ CTS = 20 log(V_{OUT}/V_{IN}) \\ BW = IHF - A \end{array} $	
INPUT	Common Mode Rejection Ratio *	CMRR	50	65	-	dB	DP1 and DN input DP2 and DN input CMRR=20log(VIN/VOUT) BW = IHF-A	
GAIN	Minimum Input Gain	Gin_min	-2	0	+2	dB	Input gain 0dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )	
INPUT G	Maximum Input Gain	Gin_max	18	20	22	dB	Input gain 20dB V <sub>IN</sub> =100mVrms G <sub>IN</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> )	
	Gain Set Error	$G_{\text{IN}\_\text{ERR}}$	-2	0	+2	dB	GAIN=+1dB to +20dB	

## **Electrical Characteristics - continued**

X			Limit					
BLOCK	Parameter	Symbol	Min	Тур	Max	Unit	Conditions	
MUTE	Mute Attenuation *	Gmute	-	-105	-85	dB	Mute ON G <sub>MUTE</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A	
VOLUME	Maximum Attenuation	Gv_min	-43	-40	-37	dB	Volume = -40dB Gv=20log(V <sub>OUT</sub> /V <sub>IN</sub> )	
	Attenuation Set Error 1	Gv_err1	-2	0	+2	dB	GAIN & ATT=0dB to -15dB	
Š	Attenuation Set Error 2	Gv_err2	-3	0	+3	dB	ATT=-16dB to -40dB	
(0)	Maximum Boost Gain	GB_BST	18	20	22	dB	Gain=+20dB f=100Hz V <sub>IN</sub> =100mVrms G <sub>B</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )	
BASS	Maximum Cut Gain	G <sub>B_CUT</sub>	-22	-20	-18	dB	Gain=-20dB f=100Hz V <sub>IN</sub> =2Vrms G <sub>B</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )	
	Gain Set Error	GB_ERR	-2	0	+2	dB	Gain=-20dB to +20dB f=100Hz	
щ	Maximum Boost Gain	GT_BST	18	20	22	dB	Gain=+20dB f=10kHz V <sub>IN</sub> =100mVrms G <sub>T</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )	
TREBLE	Maximum Cut Gain	G <sub>T_CUT</sub>	-22	-20	-18	dB	Gain=-20dB f=10kHz V <sub>IN</sub> =2Vrms G <sub>T</sub> =20log (V <sub>OUT</sub> /V <sub>IN</sub> )	
	Gain Set Error	Gt_err	-2	0	+2	dB	Gain=-20dB to +20dB f=10kHz	
	Maximum Attenuation *	GF_MIN	-	-100	-90	dB	Fader = -∞dB G <sub>F</sub> =20log(V <sub>OUT</sub> /V <sub>IN</sub> ) BW = IHF-A	
	Attenuation Set Error 1	GF_ERR1	-2	0	+2	dB	ATT=0dB to -15dB	
FADER	Attenuation Set Error 2	GF_ERR2	-3	0	+3	dB	ATT=-16dB to -47dB	
FAL	Attenuation Set Error 3	GF_ERR3	-4	0	+4	dB	ATT=-48dB to -62dB	
	Output Impedance	Rout	-	-	50	Ω	V <sub>IN</sub> =100mVms	
	Maximum Output Voltage	Vом	2	2.2	-	Vrms	THD+N=1 % BW=400Hz-30KHz	

VP-9690A(Average value detection, effective value display) filter by Matsushita Communication is used for \* measurement. Phase between input / output is same.

## **Typical Performance Curves**

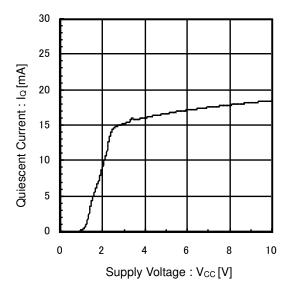


Figure 1. Quiescent Current vs Supply Voltage

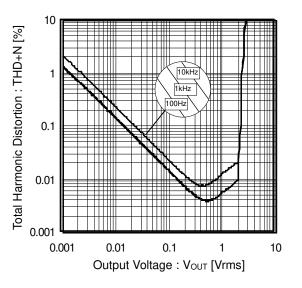


Figure 2. Total Harmonic Distortion vs Output Voltage

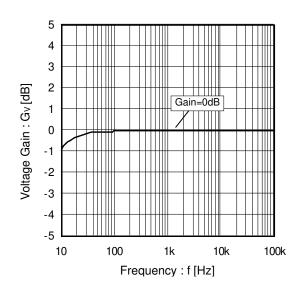


Figure 3. Voltage Gain vs Frequency

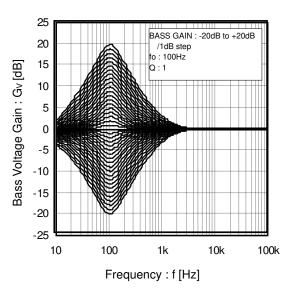


Figure 4. Bass Voltage Gain vs Frequency

## **Typical Performance Curves - continued**

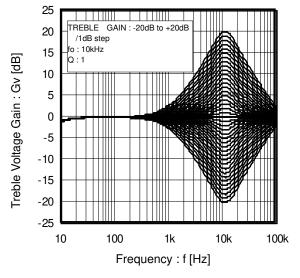


Figure 5. Treble Voltage Gain vs Frequency

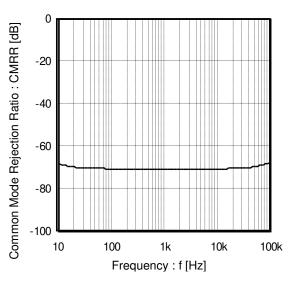


Figure 6. Common Mode Rejection Ratio vs Frequency

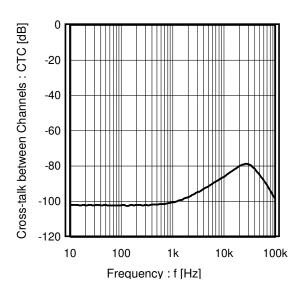


Figure 7. Cross-Talk between Channels vs Frequency

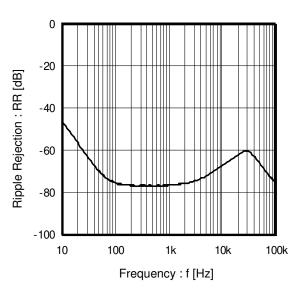


Figure 8. Ripple Rejection Ratio vs Frequency

## **Typical Performance Curves - continued**

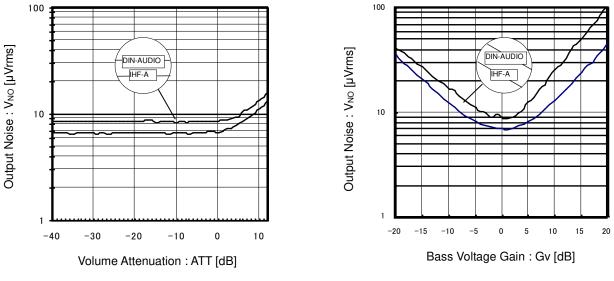
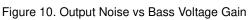


Figure 9. Output Noise vs Volume Attenuation



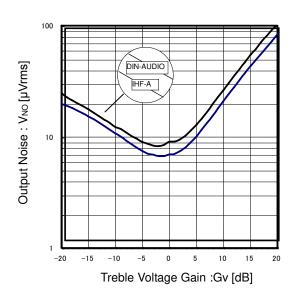


Figure 11. Output Noise vs Treble Voltage Gain

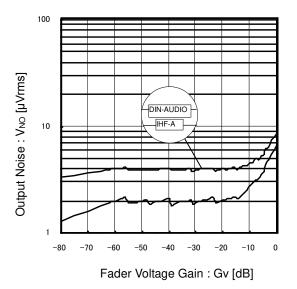


Figure 12. Output Noise vs Fader Voltage Gain

## **Typical Performance Curves - continued**

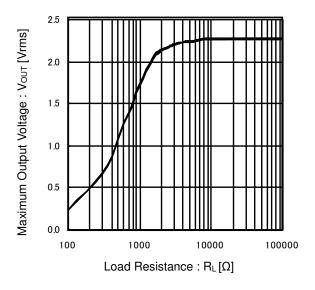


Figure 13. Maximum Output Voltage vs Load Resistance

	H2=2V AC 10:1			500us/div
HQ 10.1	HC 10.1	1		NORM:2MS/s
OUTF1	]		<b>MMM</b>	in mining
ų		ĮĘ		
⊿T 1.00ms				
1/4T 1.00000k	Iz	<u>                                     </u>		
II OUTE2		MMM	IAAAAAAAAAAAAA	LAARAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAAA
sĒ	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~			
		1		

Figure 14. Advanced Switch 1

CH1=2V CH2=2V AC 10:1 AC 10:1	500us/div NORM:2MS/s
	OUTF1
⊿T 1.00ms 1/⊿T 1.0000kHz	
	OUTF2

Figure 15. Advanced Switch 2

## **Timing Chart**

## **Control Signal Specification**

(1) Electrical Specifications and Timing for Bus Lines and I/O Stages

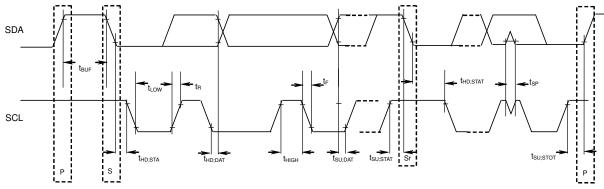


Figure 16. I<sup>2</sup>C-bus Signal Timing Diagram

#### Table 1 Characteristics of the SDA and SCL bus lines for I<sup>2</sup>C-bus devices

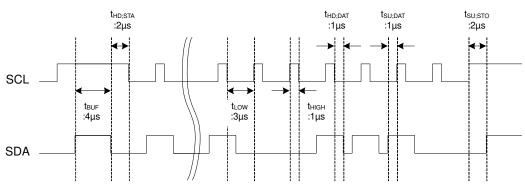
	Parameter	Symbol	Fast-mod	Unit		
	Faidilielei	Symbol	Min	Max	Unit	
1	SCL clock frequency	fscl	0	400	kHz	
2	Bus free time between a STOP and START condition	<b>t</b> BUF	1.3	-	μS	
3	Hold time (repeated) START condition. After this period, the first clock	tus est	0.0		μS	
3	pulse is generated	thd;sta	0.6	-	μο	
4	LOW period of the SCL clock	t∟ow	1.3	-	μS	
5	HIGH period of the SCL clock	tнigн	0.6	-	μS	
6	Set-up time for a repeated START condition	tsu;sta	0.6	-	μS	
7	Data hold time:	thd;dat	0.7 (Note)	-	μS	
8	Data set-up time	tsu;dat	700	-	ns	
9	Set-up time for STOP condition	tsu;sto	0.6	-	μS	

## All values referred to VIH Min and VIL Max Levels (see Table 2).

(Note) To avoid sending right after the fall-edge of SCL (VIHmin of the SCL signal), the transmitting device should set a hold time of 300ns or more for the SDA signal. For 7(t<sub>HD;DAT</sub>), 8(t<sub>SU;DAT</sub>), make the setup in which the margin is fully in.

## Table 2 Characteristics of the SDA and SCL I/O stages for I<sup>2</sup>C-bus devices

	Parameter	Sumbol	Fast-mode	Unit	
	Farameter	Symbol	Min	Max	Unit
10	LOW level input voltage:	VIL	-0.3	+1	V
11	HIGH level input voltage:	VIH	2.3	5	V
12	Pulse width of spikes which must be suppressed by the input filter.	t <sub>SP</sub>	0	50	ns
13	LOW level output voltage: at 3mA sink current	V <sub>OL1</sub>	0	0.4	V
14	Input current of each I/O pin with an input voltage between 0.4V and 4.5V.	h	-10	+10	μA



SCL clock frequency : 250 kHz



## (2) <u>I<sup>2</sup>C BUS FORMAT</u>

	MSB LSB		MSB	LSB		MSB	LSB	3		
S	Slave Address	Α	Select A	Address	Α		Data	А	Р	
 1bit	8bit	1bit		8bit	1bit		8bit	1bit	1bit	
	S	= Sta	art condition	(Recognitio	on of a	start bit)				
	Slave Address	= Re	= Recognition of slave address. The first 7 bits correspond to the slave address.							
		Th	e least signi	ficant bit is	"L" wl	hich corre	esponds to wri	ite mode	e.	
	A	= AC	KNOWLED	GE bit (Red	cognit	ion of acl	knowledgeme	nt)		
	Select Address	= Se	lect address	s correspon	ding t	o volume	e, bass or treb	le.		
Data			= Data on every volume and tone.							
	Р	= Sto	op condition	(Recognitio	on of s	stop bit)				

## (3) <u>I<sup>2</sup>C BUS Interface Protocol</u>

(a) E	Basic Format
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(¤) ·	Juolo I olimat										
S	Slave Addre	SS	Α	Select Addres	Α	A Data		Α	Р		
	MSB	LSB		MSB	LSB	Ν	ISB	LS	В		

(b)	Automatic Increment	(Select Address increases (	(+1	) according to the number of data.)
-----	---------------------	-----------------------------	-----	-------------------------------------

	S	Sla	ve Address A Select Address A Data1 A Data2 A										Dat	aN	А	Ρ		
	ľ	ИSВ	LSE	3	MSB	LSE	8 M	SB	LSB	MS	SB LS	В	Μ	SB	LS	В		
(	Exan	nple)	1 Data1 sha	all be	e set as da	ata of addi	ess	spec	ified by	Sele	ect Address.							
			<li>② Data2 sh</li>	all b	e set as da	ata of add	ress	spec	ified by	Sele	ect Address	+1.						
			③ DataN sh	all b	e set as d	ata of add	ress	spec	cified by	Sel	ect Address	+N-1	Ι.					

 (c)
 Configuration Unavailable for Transmission (In this case, only Select Address1 is set.)

 S
 Slave Address

 A
 Select Address1

S	Slave Addr	ess	Α	Select Addr	ess1	А	Dat	ta	А	Sele	ct Add	ress 2	Α	Data	Α	Ρ
	MSB	LSB		MSB	LSB	Μ	SB	LSE	3	MSB	LSB	MSB	LS	В		
	(Note) I	fany	data	a is transmitte	d as Se	elec	t Add	fress	s 2 n	ext to	data, it	t is reco	gniz	zed		
		as c	data	, not as Selec	t Addre	ss a	2.						-			

## (4) <u>Slave Address</u>

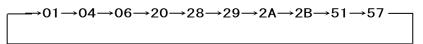
Ν	<b>/</b> SB							LSB	
Ī	A6	A5	A4	A3	A2	A1	A0	R/W	
	1	0	0	0	0	0	0	0	80H

## (5) Select Address & Data

	Select	MSB			Da	ata			LSB		
Items	Address (hex)	D7	D6	D5	D4	D3	D2	D1	D0		
Initial setup 1	01	Advance d switch ON/OFF	0	tim	ed switch e of one/Fader	0	0	Advance time of			
Input Selector	04	0	0	0	0	0		Input selecto	or		
Input gain	06	Mute ON/OFF	0								
Volume gain	20	1	0			Volume A	ttenuation				
Fader 1ch Front	28	1	0			Fader At	tenuation				
Fader 2ch Front	29	1	0			Fader At	tenuation				
Fader 1ch Rear	2A	1	0			Fader At	tenuation				
Fader 2ch Rear	2B	1	0			Fader At	tenuation				
Bass gain	51	Bass Boost/ Cut	0	0			Bass Gai	n			
Treble gain	57	Treble Boost/ Cut	0	0	Treble Gain						
System Reset	FE	1	0	0	0	0	0	0	1		
							Adva	anced switch			

Note

- 1. The Advanced Switch works in the latch part while changing from one function to another.
- 2. When changing a tone into the cut from the boost, or the cut and the boost, always go via the condition of the tone 0dB.
- 3. Upon continuous data transfer, the Select Address rolls over because of the automatic increment function, as shown below.



- 4. For the function of Input Selector etc, Advanced Switch is not used. Therefore, please apply mute on the set side when changing these settings.
- 5. When using mute function of this IC at the time of changing input selector, please switch mute ON/OFF while waiting for advanced-mute time.

Select address 01 (hex)

Mode	MSB		Adv	vanced swit	ch time of N	lute		LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
0.6msec	Advanced						0	0
1.2msec	Advanced Switch	0	Advanced	switch time	0	0	0	1
2.4msec	ON/OFF		of Volume/	Tone/Fader		0	1	0
4.8msec							1	1

Mode	MSB	Volume/Tone/Fader									
	D7	D6	D5	D4	D3	D2	D1	D0			
4.6 msec			0	0							
9.3 msec	Advanced	0		0	1	•	0	Advanced switch			
18.6 msec	<ul> <li>Switch</li> <li>ON/OFF</li> </ul>		1	0	0	0	Time o	of Mute			
37.2 msec			1	1							

Mode	MSB		ļ	Advanced sv	vitch ON/OF	F		LSB
Mode	D7	D6	D5	D4	D3	D2	D1	D0
OFF	0	0	Advanced	switch time	0	0	Advanced switch	
ON	1	0	of Volume/Tone/Fader		0	0	Time of Mute	

Select address 04(hex)

Mode	MSB			Input Sel	ector			LSB
NIOUE	D7	D6	D5	D4	D3	D2	D1	D0
A						0	0	0
В						0	0	1
С						0	1	0
D	0	0	0	0	0	1	0	0
SHORT						1	0	1
INPUT MUTE						1	1	0
						1	1	1

: Initial condition

 $\begin{array}{l} \text{SHORT}: \text{The input impedance of each input terminal is lowered from 100k} \Omega(\text{TYP}) \text{ to 6 k} \Omega(\text{TYP}). \\ (\text{For quick charge of coupling capacitor}) \end{array}$ 

INPUT MUTE : Mute is done at the input signal part of Input Selector.

#### Select address 06 (hex)

Coin	MSB			Inpu	t Gain			LSB																
Gain	D7	D6	D5	D4	D3	D2	D1	D0																
0dB				0	0	0	0	0																
1dB				0	0	0	0	1																
2dB				0	0	0	1	0																
3dB				0	0	0	1	1																
4dB				0	0	1	0	0																
5dB				0	0	1	0	1																
6dB				0	0	1	1	0																
7dB				0	0	1	1	1																
8dB				0	1	0	0	0																
9dB				0	1	0	0	1																
10dB				0	1	0	1	0																
11dB	Mute			0	1	0	1	1																
12dB	ON/OFF	0	0	0	1	1	0	0																
13dB				0	1	1	0	1																
14dB				0	1	1	1	0																
15dB				0	1	1	1	1																
16dB				1	0	0	0	0																
17dB				1	0	0	0	1																
18dB			-		-	-														1	0	0	1	0
19dB													1	0	0	1	1							
20dB				1	0	1	0	0																
				1	1	0	1	1																
Prohibition				:	:	•••	•••	:																
(Noto) In case conding pro				1	1	1	1	1																

(Note) In case sending prohibited data, 0dB is set.

Mada	MSB			Mute	Mute ON/OFF					
Mode	D7	D6	D5	D4	D3	D2	D1	D0		
OFF	0	0	0			Innut Cain				
ON	1	0	0			Input Gain				

:Initial condition

## Select address 20 (hex)

Gain & ATT	MSB			Vol Atte	enuation			LSB					
Gain & ATT	D7	D6	D5	D4	D3	D2	D1	D0					
0dB			0	0	0	0	0	0					
-1dB			0	0	0	0	0	1					
-2dB			0	0	0	0	1	0					
•			•	•	•	•	•	•					
•			•	•	•	•	•	•					
•			•	•	•	•	•	•					
-38dB	1	0	1	0	0	1	1	0					
-39dB		Ū	1	0	0	1	1	1					
-40dB			1	0	1	0	0	0					
								1	0	1	0	0	1
Prohibition				:	:	:	:	:	:				
Prohibition			1	1	1	1	1	0					
			1	1	1	1	1	1					

(Note) In case sending prohibited data, -40dB is set.

## Select address 28, 29, 2A, 2B (hex)

Gain & ATT	MSB			Fader At	tenuation			LSB
Gairi & Al T	D7	D6	D5	D4	D3	D2	D1	D0
0dB			0	0	0	0	0	0
-1dB			0	0	0	0	0	1
-2dB			0	0	0	0	1	0
•			•	•	•	•	•	•
•	1	0	•	•	•	•	•	•
•			•	•	•	•	•	•
-61dB			1	1	1	1	0	1
-62dB			1	1	1	1	1	0
-∞dB			1	1	1	1	1	1

: Initial condition

#### Select address 51, 57 (hex)

Gain	MSB			Bass/Tre	eble Gain			LSB
	D7	D6	D5	D4	D3	D2	D1	D0
0dB				0	0	0	0	0
1dB				0	0	0	0	1
2dB				0	0	0	1	0
3dB				0	0	0	1	1
4dB				0	0	1	0	0
5dB				0	0	1	0	1
6dB				0	0	1	1	0
7dB				0	0	1	1	1
8dB				0	1	0	0	0
9dB				0	1	0	0	1
10dB				0	1	0	1	0
11dB	Bass/			0	1	0	1	1
12dB	Treble	0	0	0	1	1	0	0
13dB	Boost	-	-	0	1	1	0	1
14dB	/cut			0	1	1	1	0
15dB				0	1	1	1	1
16dB				1	0	0	0	0
17dB				1	0	0	0	1
18dB				1	0	0	1	0
19dB				1	0	0	1	1
20dB				1	0	1	0	0
				1	0	1	0	1
Prohibition				:	:	:	:	:
1 TOMORION				1	1	1	1	0
				1	1	1	1	1

(Note) In case sending prohibited data, 0dB is set.

Mode	MSB			Bass/Treble Boost/Cut LS					
	D7	D6	D5	D4	D3	D2	D1	D0	
Boost	0	0	0		De	aa/Trabla C	nin		
Cut	1	0	0		Da	ss/Treble Ga	am		

:Initial condition

## (6) About Power ON Reset

Built-in IC initialization is made during power on of the supply voltage. Please send initial data to all addresses at supply voltage on. And please turn on mute at the side being set until this initial data is sent.

Parameter	Symbol	Limit			Unit	Conditions	
Falameler	Symbol	Min	Тур	Max	Unit	Conditions	
Rise Time of VCC	trise	20	-	-	µsec	$V_{CC}$ rise time from 0V to 3V	
VCC Voltage of Release Power ON Reset	VPOR	-	4.1	-	V		

## (7) About External Compulsory Mute Terminal

It is possible to force mute externally by setting an input voltage to the MUTE terminal.

Mute Voltage Condition	Mode
GND to 1.0V	MUTE ON
2.3V to Vcc	MUTE OFF

Establish the voltage of MUTE in the condition to be defined.

## **Application Information**

## 1. Function and Specifications

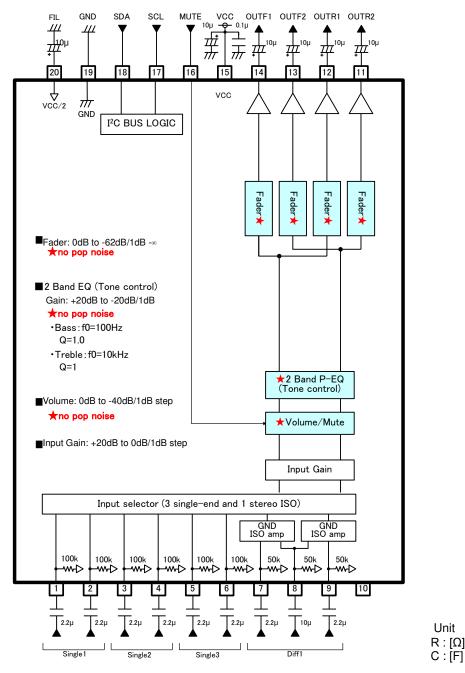
Function	Specifications
Input selector	Stereo 3 input
input selector	Differential 1 input
Input gain	OdB to 20dB
Mute	Possible to use "Advanced switch" for prevention of switching noise.
Volume	· 0dB to -40dB (1dB step)
volume	Possible to use "Advanced switch" for prevention of switching noise.
	· -20dB to +20dB (1dB step)
Bass	• Q=1
Dass	• fo=100Hz
	<ul> <li>Possible to use advanced switch at changing gain</li> </ul>
	· -20dB to +20dB (1dB step)
Treble	• Q=1
Treble	• fo=10kHz
	Possible to use advanced switch at changing gain
Fader	<ul> <li>0dB to -62dB(1dB step), -∞dB</li> </ul>
r auer	Possible to use "Advanced switch" for prevention of switching noise.

## 2. Volume / Fader Volume Attenuation Data

(dB)	D7	D6	D5	D4	D3	D2	D1	D0	(dB)	D7	D6	D5	D4	D3	D2	D1	D0
0			0	0	0	0	0	0	-32			1	0	0	0	0	0
-1			0	0	0	0	0	1	-33			1	0	0	0	0	1
-2			0	0	0	0	1	0	-34			1	0	0	0	1	0
-3			0	0	0	0	1	1	-35			1	0	0	0	1	1
-4			0	0	0	1	0	0	-36			1	0	0	1	0	0
-5			0	0	0	1	0	1	-37			1	0	0	1	0	1
-6			0	0	0	1	1	0	-38			1	0	0	1	1	0
-7			0	0	0	1	1	1	-39			1	0	0	1	1	1
-8			0	0	1	0	0	0	-40			1	0	1	0	0	0
-9			0	0	1	0	0	1	-41			1	0	1	0	0	1
-10			0	0	1	0	1	0	-42			1	0	1	0	1	0
-11			0	0	1	0	1	1	-43			1	0	1	0	1	1
-12			0	0	1	1	0	0	-44			1	0	1	1	0	0
-13			0	0	-	1	0	1	-45			1	0	-	1	0	1
-14			0	0	-	1	1	0	-46			1	0	-	1	-	0
-15	1	0	0	0	1	1	1	1	-47	1	0	1	0	1	1	1	1
-16	I	0	0	1	0	0	0	0	-48	I	0	1	1	0	0	0	0
-17			0	1	0	0	0	1	-49			1	1	0	0	0	1
-18			0	1	0	0	1	0	-50			1	1	0	0	1	0
-19			0	1	0	0	1	1	-51			1	1	0	0	1	1
-20			0	1	0	1	0	0	-52			1	1	0	1	0	0
-21			0	1	0	1	0	1	-53			1	1	0	1	0	1
-22			0	1	0	1	1	0	-54			1	1	0	1	-	0
-23			0	1	0	1	1	1	-55			1	1	0	1	-	1
-24			0	1	-	0	0	0	-56			1	1	-	0	0	0
-25			0	1	-	0	0	1	-57			1	1	-	0	0	1
-26			0	1	-	0	1	0	-58			1	1	-	0	-	0
-27			0	1	-	0	1	1	-59			1	1	-	0	-	1
-28			0	1	1	1	0	0	-60			1	1	1	1	0	0
-29			0	1	1	1	0	1	-61			1	1	1	1	0	1
-30			0	1	1	1	1	0	-62			1	1	1	1	1	0
-31			0	1	1	1	1	1	- 8			1	1	1	1	1	1
For Volume	e atter	nuatio	n, only	y 0dB	to -40	)dB ar	re ava	ilable.							المتعاد		مر م المالي

: Initial condition

3. Application Circuit



## Notes on Wiring

- ① Please connect the decoupling capacitor of the power supply in the shortest possible distance to GND.
- ② GND lines shall be one-point connected.
- ③ Wiring pattern of Digital should be away from that of Analog unit and cross-talk should not be acceptable.
- ④ SCL and SDA lines of I<sup>2</sup>C BUS should not be parallel if possible.
- The lines should be shielded, if they are adjacent to each other.

5 Analog input lines should not be parallel if possible. The lines should be shielded, if they are adjacent to each other.

## **Power Dissipation**

#### About the thermal design of the IC

Characteristics of an IC have a great deal to do with the temperature at which it is used, and exceeding absolute maximum ratings may degrade and destroy the device. Careful consideration must be given to the heat of the IC from the two standpoints of immediate damage and long-term reliability of operation.

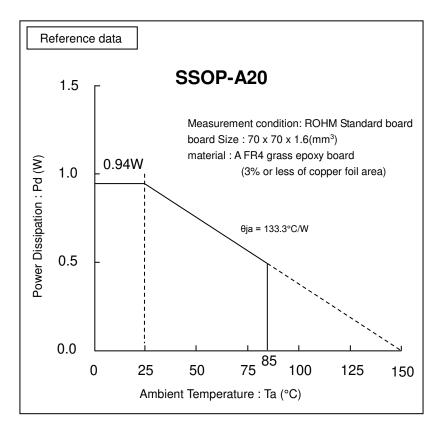


Figure 18. Temperature Derating Curve

(Note) Values are actual measurements and are not guaranteed.

Power dissipation values vary according to the board on which the IC is mounted.

## **I/O Equivalent Circuits**

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
1 2 3 4 5 6	A1 A2 B1 B2 C1 C2	4.25		A terminal for signal input. The input impedance is 100kΩ(typ).
7 9	DP1 DP1	4.25		A terminal for positive input of ground isolation amplifier. The input impedance is 50kΩ(typ).
8	DN	4.25	VCC	A terminal for negative input of ground isolation amplifier. The input impedance is 12.5kΩ(typ).
16	MUTE	-	VCC A B C C C C C C C C C C C C C	A terminal for external compulsory mute. If terminal voltage is High level, the mute is off. And if the terminal voltage is Low level, the mute is on.
11 12 13 14	OUTR2 OUTR1 OUTF2 OUTF1	4.25	VCC GND GND	A terminal for fader and Subwoofer output.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

## I/O Equivalence Circuits - continued

Terminal No.	Terminal Name	Terminal Voltage	Equivalent Circuit	Terminal Description
15	VCC	8.5		Power supply terminal.
17	SCL	-	VCC	A terminal for clock input of I <sup>2</sup> C BUS communication.
18	SDA	-	VCC	A terminal for data input of I <sup>2</sup> C BUS communication.
19	GND	0		Ground terminal.
20	FIL	4.25		Voltage for reference bias of analog signal system. The simple precharge circuit and simple discharge circuit for an external capacitor are built in.

Values in the pin explanation and input/output equivalent circuit are reference values only and are not guaranteed.

## **Operational Notes**

## 1. Reverse Connection of Power Supply

Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply pins.

## 2. Power Supply Lines

Design the PCB layout pattern to provide low impedance supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.

## 3. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

## 4. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

## 5. Thermal Consideration

Should by any chance the power dissipation rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, increase the board size and copper area to prevent exceeding the Pd rating.

## 6. Recommended Operating Conditions

These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.

## 7. Inrush Current

When power is first supplied to the IC, it is possible that the internal logic may be unstable and inrush current may flow instantaneously due to the internal powering sequence and delays, especially if the IC has more than one power supply. Therefore, give special consideration to power coupling capacitance, power wiring, width of ground wiring, and routing of connections.

## 8. Operation Under Strong Electromagnetic Field

Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.

## 9. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

## 10. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

## 11. Unused Input Pins

Input pins of an IC are often connected to the gate of a MOS transistor. The gate has extremely high impedance and extremely low capacitance. If left unconnected, the electric field from the outside can easily charge it. The small charge acquired in this way is enough to produce a significant effect on the conduction through the transistor and cause unexpected operation of the IC. So unless otherwise specified, unused input pins should be connected to the power supply or ground line.

## **Operational Notes – continued**

## 12. Regarding the Input Pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode. When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

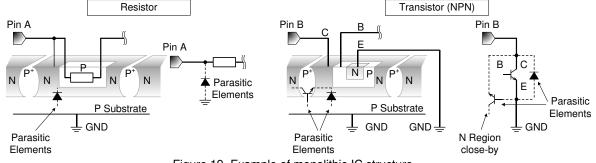
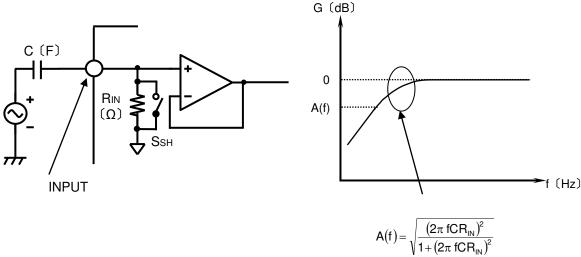


Figure 19. Example of monolithic IC structure

## 13. About a Signal Input Part

(a) About Input Coupling Capacitor Constant Value

In the input signal terminal, please decide the constant value of the input coupling capacitor C(F) that would be sufficient to form an RC characterized HPF with input impedance  $R_{IN}(\Omega)$  inside the IC.



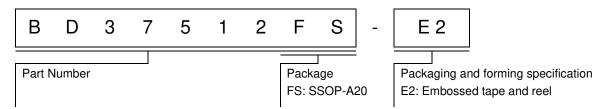
(b) About the Input Selector SHORT

SHORT mode is the command which makes switch  $S_{SH} = ON$  of input selector part so that the input impedance  $R_{IN}$  of all terminals becomes small. Switch  $S_{SH}$  is OFF when SHORT command is not selected. The constant time brought about by the small resistance inside and the capacitor outside the LSI becomes small when this command is used. The charge time of the capacitor becomes short. Since SHORT mode turns ON the switch of  $S_{SH}$  and makes it low impedance, please use it at no signal condition.

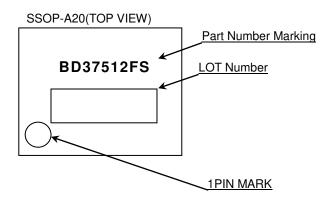
## 14. About Mute Terminal(Pin 16) when power supply is OFF

There should be no applied voltage across the Mute terminal (Pin 16) when power-supply is OFF. A resistor (about  $2.2k\Omega$ ) should be connected in series to Mute terminal in case a voltage is supplied to Mute terminal. (Please refer Application Circuit Diagram.)

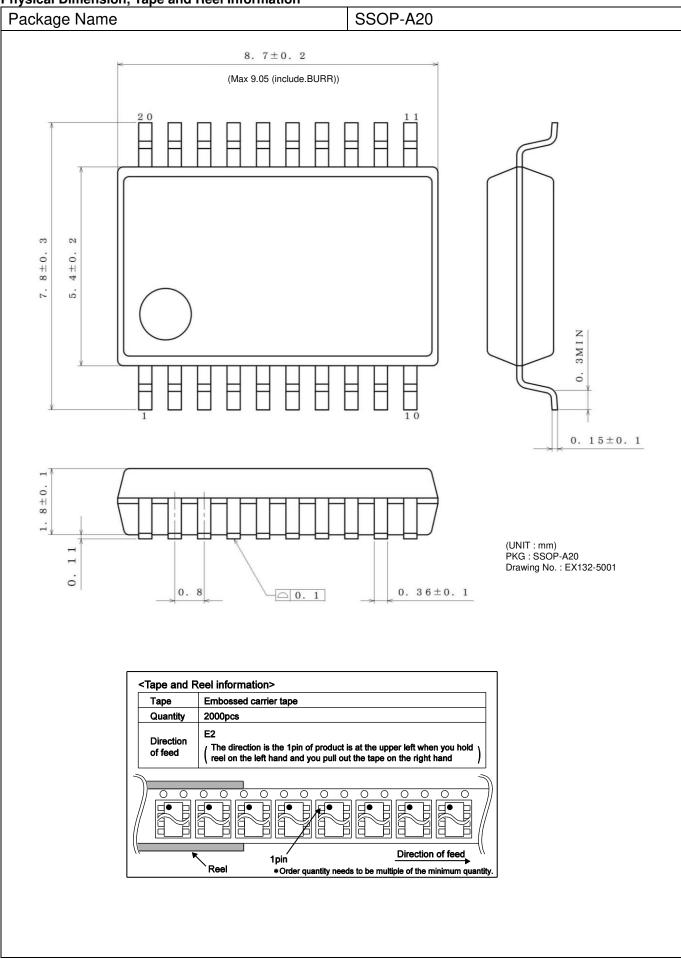
## **Ordering Information**



## **Marking Diagram**



## Physical Dimension, Tape and Reel Information



## **Revision History**

	Date	Revision	Changes
1	6.Dec.2015	001	New Release

# Notice

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-----------------------------------------------------------------------

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSIII	CLASSⅢ	CLASSII

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
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